

What is claimed is:

1. A semiconductor device comprising:

a semiconductor element including an electrode formed on an electrode-formed surface thereof;

5 a reinforcing member bonded to a back surface of said semiconductor element, said back surface being opposite to said electrode-formed surface; and

an adhesive bonding said semiconductor element and said reinforcing member while allowing said semiconductor element to be deformed.

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2. The semiconductor device of claim 1, wherein said adhesive is made of resin having a low elastic modulus, and bonds said back surface of said semiconductor element entirely to said reinforcing member.

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3. The semiconductor device of claim 1, wherein said adhesive bonds only a center of said back surface of said semiconductor element to said reinforcing member.

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4. The semiconductor device of claim 1, wherein said reinforcing member has a flexural rigidity greater than a flexural rigidity of said semiconductor element.

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5. The semiconductor device of claim 1, wherein said reinforcing member is larger than said semiconductor element in outside shape.

6. The semiconductor device of claim 5, wherein said reinforcing member includes:

a recess portion to which said semiconductor element is bonded; and
a projection formed at a border of said recess portion.

7. The semiconductor device of claim 1, wherein said reinforcing
5 member functions as a holding member in handling.

8. The semiconductor device of claim 1, wherein an identification
information is applied to an applied surface of said reinforce member, said
applied surface being opposite to a surface bonded to said semiconductor
10 element.

9. A method of manufacturing a semiconductor device, comprising the
steps of:

shaving a back surface of a semiconductor wafer, said back surface
15 being opposite to an electrode-formed surface of said semiconductor wafer
including a plurality of semiconductor elements therein;

bonding a reinforcing plate to the shaved back surface of the
semiconductor wafer with an adhesive; and

dividing the semiconductor wafer to which the reinforcing member is
20 bonded and the reinforcing plate into units of the semiconductor elements.

10. The method of claim 9, wherein said step of dividing the
semiconductor wafer and the reinforcing plate includes the sub step of
dividing the reinforcing plate with a dicing width smaller than a dicing width
25 of the semiconductor wafer.

11. The method of claim 9, further comprising the step of attaching a

